

**Date:** October 2019  
**Rev:** IX  
**No. of Components:** Two  
**Mix Ratio by Weight:** 10 : 1  
**Specific Gravity:** Part A: 1.12      Part B: 1.02  
**Pot Life:** 3 Hours  
**Shelf Life- Bulk:** One year at room temperature

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):

*May not achieve performance properties listed below*

150°C / 1 Minute

120°C / 5 Minutes

100°C / 10 Minutes

#### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.
- **TOTAL MASS SHOULD NOT EXCEED 25 GRAMS**

**Product Description:** EPO-TEK® 353ND-T is a two component, highly thixotropic epoxy with non-flowing properties and high temperature resistance.

**Typical Properties:** Cure condition: 150°C / 1 Hour      Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:					
* Color (before cure):	Part A: Tan	Part B: Amber			
* Consistency:	Smooth thixotropic paste				
* Viscosity (23°C) @ 20 rpm:	9,000 - 15,000	cPs			
Thixotropic Index:	3.8				
* Glass Transition Temp:	≥ 90	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)			
Coefficient of Thermal Expansion (CTE):					
Below Tg:	43	x 10 <sup>-6</sup> in/in°C			
Above Tg:	231	x 10 <sup>-6</sup> in/in°C			
Shore D Hardness:	80				
Lap Shear @ 23°C:	1,953	psi			
Die Shear @ 23°C:	≥ 15	Kg	5,334	psi	
Degradation Temp:	409	°C			
Weight Loss:					
@ 200°C:	0.53	%			
@ 250°C:	1.22	%			
@ 300°C:	2.37	%			
Suggested Operating Temperature:	< 325	°C (Intermittent)			
Storage Modulus:	559,120	psi			
Ion Content:	Cl <sup>-</sup> :	471 ppm	Na <sup>+</sup> :	143	ppm
	NH <sub>4</sub> <sup>+</sup> :	400 ppm	K <sup>+</sup> :	15	ppm
* Particle Size:	99% ≤ 20	microns			
ELECTRICAL AND THERMAL PROPERTIES:					
Thermal Conductivity:	N/A				
Volume Resistivity @ 23°C:	≥ 4 x 10 <sup>12</sup>	Ohm-cm			
Dielectric Constant (1KHz):	3.21				
Dissipation Factor (1KHz):	0.003				

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**EPO-TEK® 353ND-T Advantages & Suggested Application Notes:**

- Suitable for fiber optic and circuit assembly applications.
- Recommended for bonding metals, glass, ceramics and many types of plastic.
- High temperature adhesive for hybrids and medical devices; it can resist within the 300°C range for long periods of time.
- Circuit assembly applications; staking SMD's to PCB, bonding ferrite cores together in copper coil windings, inductor coils and power devices; suitable for COB glob top DAM material.
- Alternative product versions available with distinct viscosity ranges - contact Technical Services at [techserv@epotek.com](mailto:techserv@epotek.com) for best recommendation.
- Can be applied by screen printing, spatula, hand held or automatic dispensing equipment.
- Amber color change when properly cured for easy visual ID and inspection.

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